CYBERDYNE

Recruiting Students for the 2025 Academic Year!
[Cybernics Future Pioneering Talent Development Program]
Scholarships × AI & HCPS Integration and Cutting-Edge Technology Internship

1. Purpose of the Program

The Company is a future-oriented enterprise that simultaneously promotes the creation of innovation, the development of new industries, and talent cultivation through the integration of "Human" and "Human-Cyber-Physical Space" (HCPS), utilizing Cybernics(*) to address various societal challenges. By fostering a virtuous cycle of innovation, the aim is to generate new technologies and cultivate skilled professionals in these fields.

As part of efforts in future-oriented talent development, the 2025 Cybernics Future Pioneering Talent Development Program: Scholarships × AI & HCPS Integration and Cutting-Edge Technology Internship will be offered to graduate students with a strong motivation to engage in the fields that comprise Cybernics.

A broad call for applications will be made, followed by a rigorous review and selection process. Applications from enthusiastic candidates are eagerly awaited.

2. Overview

(1)	Number of Participants	A selected number of participants.
(2)	Application Period	From February 10, 2025 (Monday) to March 31, 2026 (Tuesday)
(3)	Selection Process	Document screening and final selection will be conducted on a rolling basis for each application.
(4)	Program Duration	In principle, from the start, the program will follow the standard minimum duration of study (up to a maximum of 3 years).
(5)	Scholarship Amount	¥200,000 per month (¥100,000 as a grant, ¥100,000 as a loan) If employed by the Company for 5 years after the program, the entire amount will be granted.
(6)	Scholarship Payment Method	Payments will be transferred to the applicant's personal bank account by the 25th of each month.
(7)	Restrictions on Concurrent Scholarships	Concurrent use of other scholarships is not permitted, or the scholarship amount may be adjusted (based on individual assessment).
(8)	Start of Payment	April 2025 The start month for payments can be changed upon consultation.

3. Eligibility

(1) Individuals who are planning to enter or are currently enrolled in a doctoral program.

(2) Individuals majoring in fields that constitute Cybernics, such as artificial intelligence and artificial brains, human-robot collaboration, information technology (IT), neuroscience, regenerative medicine, cyberspace construction, system integration technologies, and related disciplines. Additionally, the following candidates will be given preferential consideration:

- Those capable of handling ROS2 and advancing research and development related to VSLAM.
- Those capable of advancing research and development in NLP (including LLMs and multimodal models).

- Those capable of advancing research and development in data analysis and signal processing (including algorithm development and program implementation).
- (3) Individuals who are able to participate in internships at the Company.

4. Application Documents and Selection Method
   - (1) Application Documents:
     - ① Resume (free format)
     - ② Enrollment certificate from the current university
     - ③ Academic transcript (most recent completed course)
     - ④ "Details of publicly disclosed research achievements and reasons for applying to this program" (approximately 2,000 words)

       Please send the application documents to **internship@cyberdyne.jp** within the application period.

       Note: Application documents will not be returned.
   - (2) Selection Method:

     The selection process will consist of document screening followed by an interview.

     Those who pass the document screening will be contacted separately regarding the interview date.

5. Scholarship Payment
   - (1) The scholarship consists of a non-repayable grant portion and a repayable loan portion.
   - (2) After graduation, the career path of the scholarship recipient is open, but if employed by the Company for 5 years after completing the program (following graduation), the entire loan amount will be waived, and the scholarship will be fully granted.

6. Repayment of the Loan Portion of the Scholarship
   - (1) The repayment period for the loan portion of the scholarship will be determined through discussions between the Company and the scholarship recipient at the end of the loan period.
   - (2) The repayment period, in principle, cannot exceed five times the duration of the loan period.
   - (3) No interest will be charged on the loan amount.
   - (4) If the scholarship recipient neglects their obligations during the program (refer to "8. Responsibilities of the Scholarship Recipient" and "9. Loss of Scholarship Eligibility"), the scholarship will be suspended, and the loan amount already provided must be repaid in a lump sum, in principle.

7. Internship

   The internship will involve working with cutting-edge technologies like AI & HCPS integration. Discussions between the Company and the scholarship recipient will determine the specific details and content.

8. Responsibilities of the Scholarship Recipient
   - (1) The scholarship must be used for academic and research purposes. The recipient should also pay attention to health by, for example, refraining from smoking and maintaining an attitude and behavior appropriate for a scholarship recipient.
   - (2) The recipient must participate in the internship associated with the program and work earnestly on the assigned tasks.
   - (3) During the program, the recipient must report academic transcripts and academic status as requested by the Company.
   - (4) After being selected as a scholarship recipient, if there are any changes to the recipient's contact information, enrollment status, or other circumstances, they must promptly notify the Company.

    (5) The recipient must submit a pledge form with a guarantor's signature.

9.   Loss of Scholarship Eligibility

   The scholarship recipient will lose eligibility under the following circumstances:

     ①   If they take a leave of absence.

     ②   If they are suspended.

     ③   If their academic or internship performance or conduct is poor.

     ④   If they fail to comply with the Company's requests to fulfill the responsibilities outlined in "8. Responsibilities of the Scholarship Recipient."

     ⑤   If they lose their student status.

     ⑥   If they voluntarily withdraw from the scholarship.

     ⑦   If it is found that they are involved with antisocial forces.

     ⑧   If there are any other facts deemed inappropriate for a scholarship recipient.

10.   Handling of Personal Information

   Personal information obtained from the application documents will only be used for the purposes of screening, preparing internal statistical materials, and contacting the applicant directly.

11.   Contact

   For any uncertainties, please contact the following

> Secretariat：CYBERDYNE Inc. Corporate Department Internship Team
> Address: 2-2-1 Gakuen-minami, Tsukuba, Ibaraki, 305-0818, Japan
> Email: internship@cyberdyne.jp

*What is Cybernics

  Cybernics is a new academic field that integrates Cybernetics, Mechatronics, Informatics, and various other disciplines such as neuroscience, regenerative medicine, robotics, IT, and ethics. The aim is to create a fusion of human, AI robots, and information systems, leading to groundbreaking innovations in a Human Cyber Physical Space (HCPS). The complexity of real-world issues often involves multifaceted challenges that cannot be solved by traditional approaches alone, but Cybernics offers a holistic and interdisciplinary solution to these complex problems. Efforts to create an innovation spiral between basic research and practical application centered around Cybernics are being promoted through major research and development programs in Japan, including the Cabinet Office FIRST Program and ImPACT Program, as well as international educational research initiatives such as the Ministry of Education, Culture, Sports, Science and Technology (MEXT) Global COE, Leading Graduate Schools, and Excellence in Graduate Schools programs. Additionally, the third phase of the Cabinet Office's SIP Program is expanding these efforts. Innovative advancements in the Cybernics field are also emerging as national projects in various foreign governments.